

20-3241 FLEXIBLE EPOXY RESIN POTTING AND ENCAPSULATING COMPOUND

DESCRIPTION:

20-3241 is a two component high purity grade polymer epoxy system. This is a low viscosity formulation designed for encapsulation where low embedment stress to sensitive electronic components is required.

20-3241 has excellent adhesion to metals, plastics, ceramics, glass, copper, and aluminum.

FEATURES:

Low viscosity
 Bubble free castings
 Excellent vibration resistance
 Outstanding electrical properties

TYPICAL SPECIFICATIONS:

Mixed viscosity @ 25°C, cps	1,000
Color	Black (Clear version available)
Pot life with 20-3241C Hardener	30 - 45 Minutes
Specific gravity, 25°C	
Resin	1.15
Catalyst	0.95
Hardness, shore A	75
Shrinkage linear in/in	0.006
Operating temperature range, °C	-50 to +100
Thermal conductivity, W/m- °K	0.42
Thermal expansion coefficient per °C	50 x 10 ⁻⁶
Dielectric strength Volts/Mil	560
Dielectric constant at 60 Hz	4.7
Dissipation factor at 60 Hz	.034
Volume resistivity, ohm-cm	5.0×10^{15}

INSTRUCTIONS FOR USE:

ROOM TEMPERATURE CURING 20-3241C HARDENER

- 1. By weight thoroughly mix 50 parts 20-3241C Hardener to 100 parts 20-3241R Resin.
- 2. By volume thoroughly mix 60 parts 20-3241C Hardener to 100 parts 20-3241R Resin
- 3. Pour and follow one of the following cure schedules:
 - a) 25°C 18-24 Hours b) 60°C 1-2 Hours



IMPORTANT:

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